Specification of Thermoelectric Module
TEHC1-01704

Description

The 17 couples, 15 mm × 15 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 70° C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

● High effective cooling and efficiency

● No moving parts, no noise, and solid-state

● Compact structure, small in size, light in weight

● Environmental friendly, RoHS compliant

● Precise temperature control

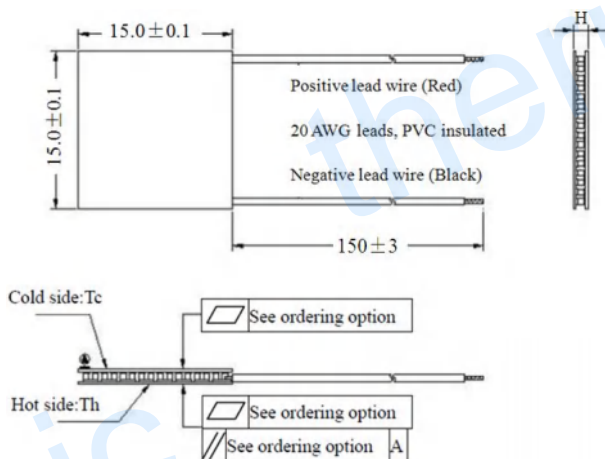● Exceptionally reliable in quality, high performance

Application

● Food and beverage service refrigerator

● Portable cooler box for cars

● Temperature stabilizer

● Liquid cooling

● CPU cooler and scientific instrument

● Photonic and medical systems

Performance Specification Sheet

T_h (ºC)	27	50	Hot side temperature at environment: dry air, N2
DTmax (ºC)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
Umax (Voltage)	2.2	2.4	Voltage applied to the module at DTmax
Imax (Amps)	4.9	4.9	DC current through the modules at DTmax
QCmax (Watts)	6.8	7.5	Cooling capacity at cold side of the module under DT=0 ºC
AC resistance (Ohms)	0.36	0.38	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters

15.0±0.1
15.0±0.1
H

Positive lead wire (Red)
20 AWG leads, PVC insulated
Negative lead wire (Black)
150±3

Cold side:Tc
See ordering option
Hot side:Th
See ordering option
See ordering option A

Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138ºC)

2. T200: CuAgSn (Tmelt = 217°C)

3. T240: SbSn (Tmelt = 240°C)

C. Ceramics:

1. Alumina (Al_2O_3, white 96%)

2. Aluminum Nitride (AlN)

B. Sealant:

1. NS: No sealing (Standard)

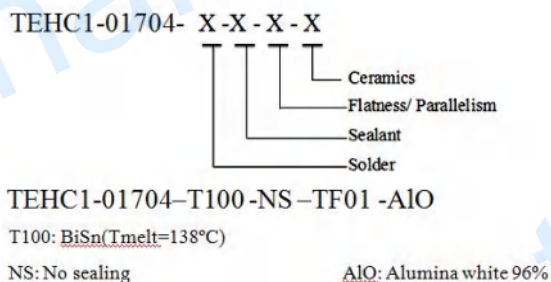2. SS: Silicone sealant

3. EPS: Epoxy sealant

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)

2. Metalized

Ordering Option

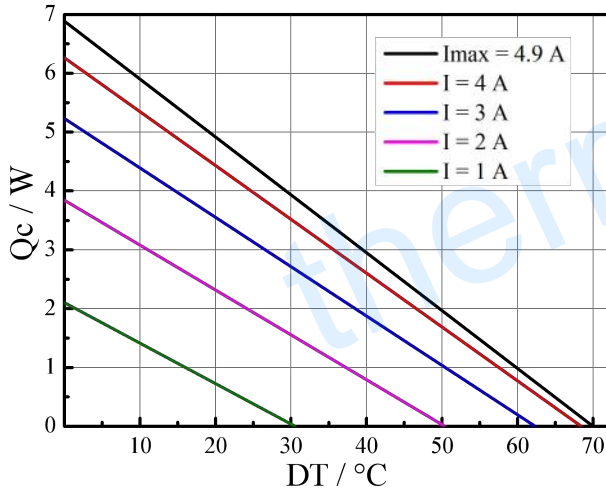| Suffix	Thickness H / (mm)	Flatness/ Parallelism (mm)	Lead wire length (mm) Standard/Optional length
TF	0:4.0±0.10	0:0.05/0.05	150±3/Specify
TF	1:4.0±0.03	1:0.02/0.02	150±3/Specify
Eg. TF01: Thickness 4.0±0.10(mm) and Flatness 0.02/0.02(mm)			

Naming for the Module

TEHC1-01704- X-X-X-X

Ceramics
Flatness/ Parallelism
Sealant
Solder

TEHC1-01704–T100 -NS –TF01 -AlO

T100: BiSn(Tmelt=138°C)

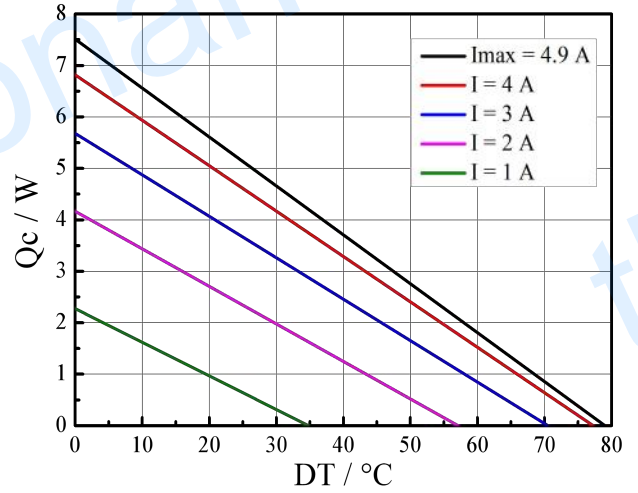NS: No sealing   AlO: Alumina white 96%

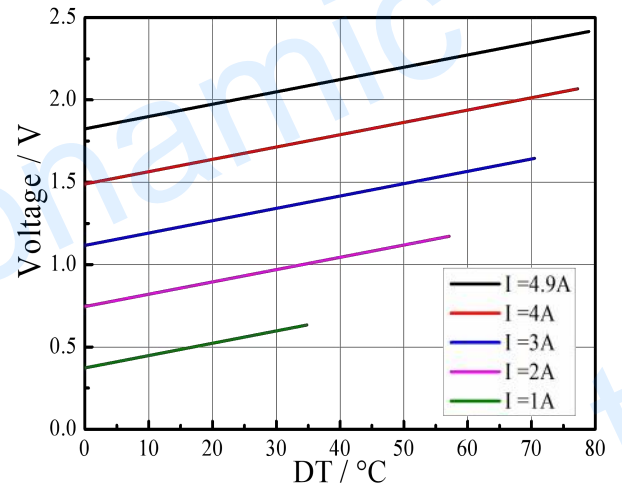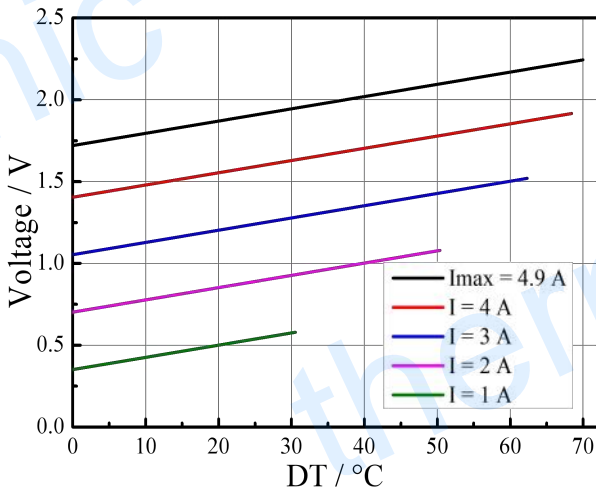# Specification of Thermoelectric Module

TEHC1-01704

Performance Curves at Th=27 ºC

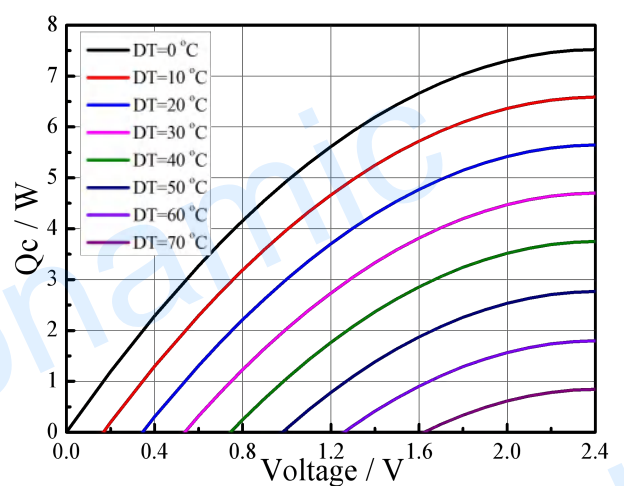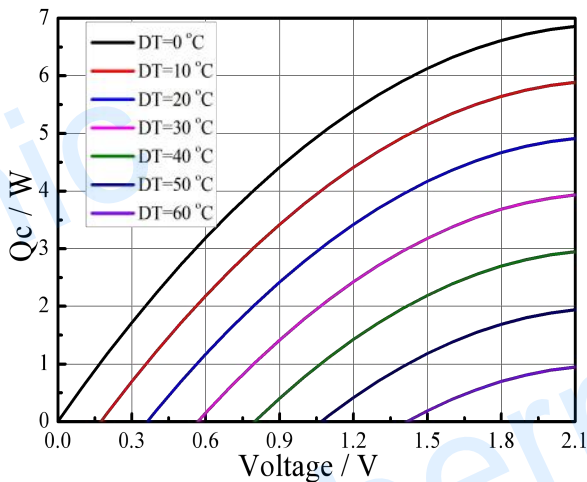### Performance Curves at Th=50 ºC

Standard Performance Graph Qc= f(DT)
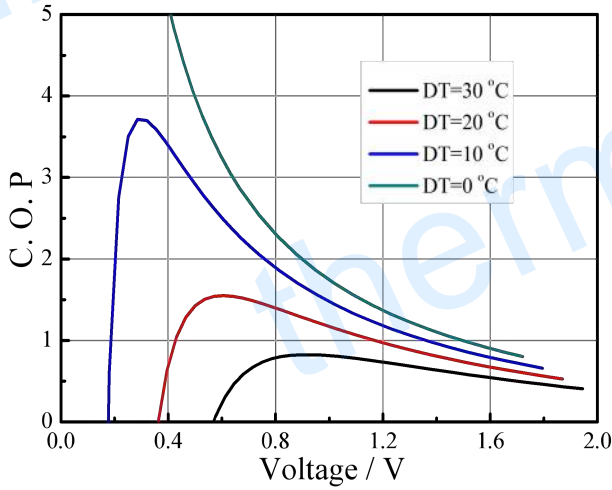
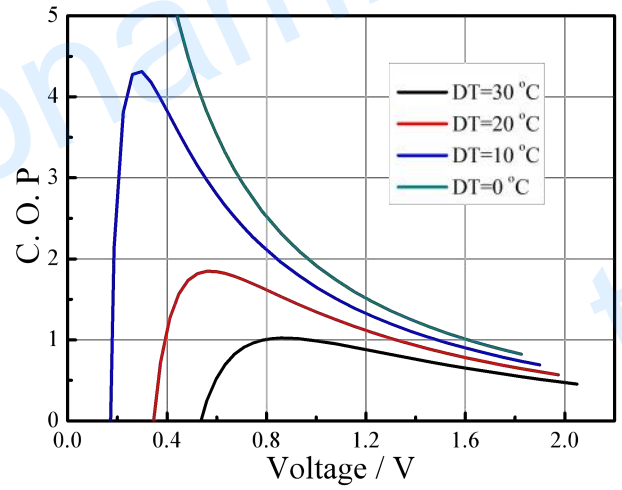Standard Performance Graph V= f(DT)

Standard Performance Graph Qc= f(V)

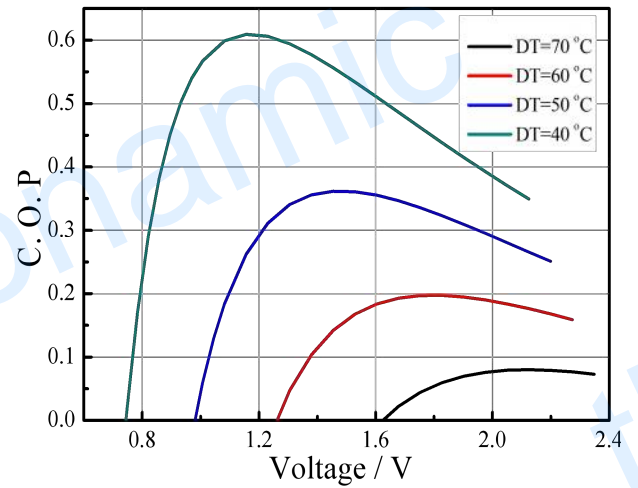# Specification of Thermoelectric Module
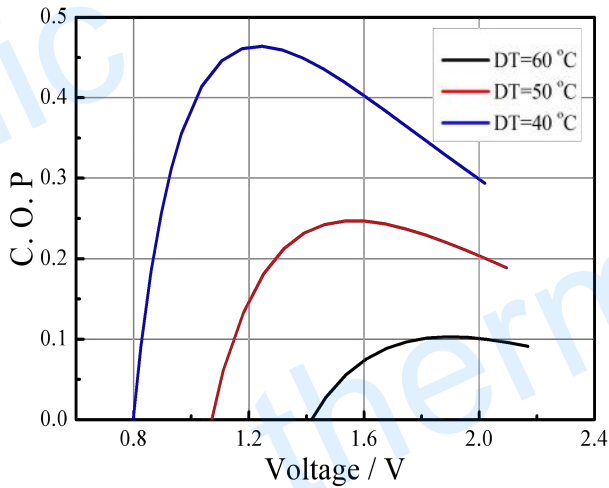
TEHC1-01704

Performance Curves at Th=27 ºC

Performance Curves at Th=50 ºC

Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 ˚C

Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 ˚C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

● Attach the cold side of module to the object to be cooled

● Attach the hot side of module to a heat radiator for heat dissipating

● Operation below I_{max} or V_{max}

● Work under DC